



## CONDITIONS FOR OBTAINING TRANSITIONAL CERTIFICATION

Revision E

09-15-99

The requirements for Transitional Certification are in paragraph H.3.3, Appendix H, of MIL-PRF-38535. As discussed in that paragraph, all facilities are subject to an audit for transitional certification. The supplier is responsible for all auditing expenses incurred by the 38535 office if off-shore facilities are audited for transitional certification. In addition, suppliers must submit the results of sections 1-A, or 1-B, as applicable, before any audits are scheduled.

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**Conditions For Obtaining Transitional Certification  
Revision E**

SECTION 1-A  
FACILITIES NOT COMPLIANT WITH APPENDIX A OF 38535

The following information is to be sent to DSCC-VQC. Indicate if not applicable (NA).

1. Circuit design: name, location, line, and flow.
2. Mask fab: name, location, line, and flow.
3. Wafer fab: name, location, line (bipolar, CMOS, biCMOS, etc.), and flow.
4. Die source (manufacturer, distributor, etc): name and location.
5. Assembly: name, location, line (e.g., single chip integrated circuit , multi-chip integrated circuit, die attach method, package material and seal technique), and flow.
6. Assembly screening (M5004): name, location, line, flow name, and list of test method numbers.
7. Electrical test: name, location, line, and flow.
8. Environmental test (M5005): name, location, line, flow, and list of test method numbers.
9. SPC program and status.
10. Lot screening and lot sampling summary for the past two years
11. Manufacturer
  - a. Number and description
    - 1) Part types to be offered as 883-compliant on QML-38535.
    - 2) Part types to be offered as Class M on QML-38535 for Standard Microcircuit Drawings (SMD's).
    - 3) Part types to be offered as Class V and Class Q on QML-38535 for SMD's
    - 4) Military part types made to customer controlled drawings (SCD's).
    - 5) Databook military part types that have been produced using the above facilities.
  - b. Product quality and facility history
    - 1) Flowcharts, travelers, baselines, and any relevant data (including internal qualification information) demonstrating that the products to be offered as QML-38535 parts meet Appendix A of 38535 and M5007, M5004, and M5005 of 883). Details for any questionable products must be resolved prior to their listing in QML-38535.
    - 2) Facility audit summary, and each facility's status, for the last two years.
    - 3) Discussion of the past and present quality standards used to control quality and reliability for each facility.

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12. Hi-Rel Assembly Service
  - a. Month and year of 1st production
  - b. For the immediate previous 3 years, names of customers, their specification, and quality level (space or non-space).
  - c. For the immediate previous 1 year, average monthly unit production.
  
13. Compliance
  - a. Perform a self-audit to determine compliance with Appendix A and develop a schedule showing how compliance will be accomplished.
  - b. Perform Section 2.
  
14. After the above information has been reviewed, selected documents may be requested, and an audit may be required to determine if the manufacturer should receive Transitional Certification. All facilities are subject to an audit. The supplier is responsible for all auditing expenses incurred by the 38535 office if off-shore facilities are audited.

SECTION 1-B  
FACILITIES COMPLIANT WITH APPENDIX A OF 38535

The following information is to be sent to DSCC-VQC. Indicate if not applicable (NA).

1. Circuit design: name, location, line, and flow.
2. Mask fab: name, location, line, and flow.
3. Wafer fab: name, location, line (bipolar, CMOS, biCMOS, etc.), and flow.
4. Die source (manufacturer, distributor, etc): name and location.
5. Assembly: name, location, line (e.g., single chip integrated circuit, multi-chip integrated circuit, die attach method, package material and seal technique), and flow.
6. Assembly screening (M5004): name, location, line, flow name, and list of test method numbers.
7. Electrical test: name, location, line, and flow.
8. Environmental test (M5005): name, location, line, flow, and list of test method numbers.
9. SPC program and status.
10. Lot screening and lot sampling summary for the past two years.

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11. Manufacturer

- a. Number and description
  - 1) Part types to be offered as 883-compliant on QML-38535.
  - 2) Part types to be offered as Class M on QML-38535 for Standard Microcircuit Drawings (SMD's).
  - 3) Part types to be offered as Class V and Class Q on QML-38535 for SMD's.
  - 4) Military part types made to customer controlled drawings (SCD's).
  
- b. Product quality and facility history
  - 1) Flowcharts, travelers, baselines, and any relevant data (including internal qualification information) demonstrating that the products to be offered as QML-38535 parts meet Appendix A of 38535 and M5007, M5004, M5005 of 883). Details for any questionable products must be resolved prior to their listing in QML-38535.
  - 2) Facility audit summary, and each facility's status, for the last two years.

12. Hi-Rel Assembly Service

- a. Month and year of 1st production
- b. For previous 3 years, names of customers, their specification, and quality level (space or non-space).

13. Compliance. Perform Section 2.

14. After the above information has been reviewed, selected documents may be requested, and an audit may be required to determine if the manufacturer should receive Transitional Certification. All facilities are subject to an audit. The supplier is responsible for all auditing expenses incurred by the 38535 office if off-shore facilities are audited.

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SECTION 2  
COMPLIANCE WITH 38535

Perform a self-audit to determine compliance with 38535 and Appendices B through J. Indicate if not applicable (NA).

1. A schedule is to be sent to DSCC-VQC showing how compliance will be accomplished. Alternate methods may be used to meet the requirements, provided it can be demonstrated that the quality and reliability issues of the requirement are addressed. Compliance with a requirement is not necessary, provided it can be demonstrated that it is not applicable to the suppliers technologies. See 38535, page 3, para 3.1.
2. The following paragraph numbers are listed in the belief that they will require the most effort to achieve full compliance. These areas should be discussed with the 38535 office to ensure an understanding of them, and to determine if the supplier's current quality system already meets the intent of the requirements.

<u>QM Program Topic</u>	<u>38535 requirement</u>	<u>38535 App. G requirement</u>
QM Program	3.3	G.3.1
Technical Review Board	3.3.1	G.3.2
Status Report	none	G.3.2.3
QM Plan	3.3.2	G.3.3
Contin. Improve.Plan	none	G.3.3a, G.3.3.1h
SPC	none	3.3c, G3.3.1i
Change Control	3.3.4	G.3.3e, G.3.4
Convert. Cust. Require.	none	G3.3.1b
Control of contractor	3.4.1.3.1	G.3.3.1r
<u>Proc. Cap. Demo.Topic</u>	<u>38535 requirement</u>	<u>38535 App. H requirement</u>
Circuit Design	none	H.3.2.1.1
Package Design	3.4.1.4.1	H.3.2.1.2
TCV Program	none	H.3.2.2.2
SEC Program	none	H.3.2.2.3
Package. Tech. Char.	none	H.3.2.4.2
Qualification	3.4.2	H.3.4

3. After the above information has been reviewed, selected documents may be requested before an audit is scheduled to determine if the manufacturer should receive Full Certification. All facilities are subject to an audit. The supplier is responsible for all auditing expenses incurred by the 38535 office if off-shore facilities are audited.